

REMARKS

Applicant thanks the Examiner for considering the arguments put forth in the December 26, 2001 Amendment for the instant Application.

Applicants thank the Examiner for removing the claim objections and indefiniteness rejections as noted in paragraph 2 of the Office Action.

Applicants thank the Examiner for removing the obviousness rejections of claims 4-6, as noted in paragraph 2 of the Office Action.

Status of the Application

Claims 1-11 and 25 are the only claims pending in the Application, as claims 12-24 are withdrawn from consideration and are hereby cancelled. Claims 1-3, 7-11 and 25 have been rejected. Claims 3, 6 and 12-24 are cancelled without prejudice or disclaimer. Claims 26-33 are added.

Allowable Subject Matter

Applicant thanks the Examiner for indicating that claims 4-6 would be allowed if rewritten in independent form.

The features of claim 6 are hereby added to independent claim 1. Thus, Applicants respectfully submit that claim 1 is now allowable, and that the remaining claims 2, 7-11 and 25 which depend from claim 1 are allowable, *at least* by virtue of that dependency.

Claim 4 is hereby rewritten in independent form. Thus, Applicants respectfully submit that claim 4 is now allowable, and that claims 5 and 26-33, which are dependent from claim 4, are allowable, *at least* by virtue of that dependency. Claims 26-33 correspond to originally filed claims 2, 3, 7-11 and 25, but are dependent from claim 4.

Claim Rejections

The Examiner has rejected claims 1-3, 7-11 and 25 under various combinations of references. However, these rejections are now believed to be moot in view of the claim amendments herein.


Conclusion

In view of the foregoing, it is respectfully submitted that claims 1, 2, 4, 5, 7-11 and 25-33 are allowable. Thus, it is respectfully submitted that the application now is in condition for allowance with all of the claims 1, 2, 4, 5, 7-11 and 25-33.

If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

Please charge any fees which may be required to maintain the pendency of this application, except for the Issue Fee, to our Deposit Account No. 19-4880.

Respectfully submitted,



Timothy P. Cremen
Registration No. 50,855

SUGHRUE MION, PLLC
2100 Pennsylvania Avenue, N.W.
Washington, D.C. 20037-3213
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

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APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 3, 6 and 12-24 are canceled.

The claims are amended as follows:

1. (Twice Amended) A semiconductor device comprising:

- (a) a substrate having a surface;
- (b) a dielectric formed over the surface of the substrate; and
- (c) a wiring line buried in the dielectric;

the wiring line including a Cu-based conductor and a first cover layer covering an outer surface of the conductor;

the first cover layer being made of refractory metal nitride;

further comprising a second cover layer provided between the conductor and the first cover layer and a third cover layer provided between the conductor and the first cover layer;

wherein the second cover layer covers partially or entirely the outer surface of the conductor, the second cover layer being made of refractory metal;

and wherein the third cover layer covers entirely or partially the outer surface of the conductor, the third cover layer being made of dielectric.

4. (Amended) [The device according to claim 1,] A semiconductor device comprising:

- (a) a substrate having a surface;
- (b) a dielectric formed over the surface of the substrate; and

(c) a wiring line buried in the dielectric;

the wiring line including a Cu-based conductor and a first cover layer covering an outer surface of the conductor;

the first cover layer being made of refractory metal nitride;

further comprising a third cover layer provided between the conductor and the first cover layer;

wherein the third cover layer covers entirely or partially the outer surface of the conductor, the third cover layer being made of dielectric.

Claims 26-33 are added.